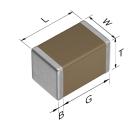
# Multilayer Ceramic Chip Capacitors

### C2012X7R2A473K125AA

| <b>Product Status</b>    | Production   |
|--------------------------|--|
| TDK Item Description     | C2012X7R2A473KT****  |
| Applications             | Commercial Grade  Please refer to Part No. <u>CGA4J2X7R2A473K125AA</u> for Automotive use. |
| Feature                  | MidMid Voltage (100 to 630V)   |
| Series                   | C2012 [EIA 0805]   |
| Status                   | Production   |
| Brand                    | TDK  |
| Environmental Compliance | ROHS REACH Halogen Free Lead Free  |



|                               | Size                               |
|-------------------------------|------------------------------------|
| Length(L)                     | 2.00mm ±0.20mm                     |
| Width(W)                      | 1.25mm ±0.20mm                     |
| Thickness(T)                  | 1.25mm ±0.20mm                     |
| Terminal Width(B)             | 0.20mm Min.                        |
| Terminal Spacing(G)           | 0.50mm Min.                        |
| Recommended Land Pattern (PA) | 1.00mm to 1.30mm(Flow Soldering)   |
| recommended Land Fattern (FA) | 0.90mm to 1.20mm(Reflow Soldering) |
| Recommended Land Pattern (PB) | 1.00mm to 1.20mm(Flow Soldering)   |
|                               | 0.70mm to 0.90mm(Reflow Soldering) |
| Recommended Land Pattern (PC) | 0.80mm to 1.10mm(Flow Soldering)   |
| necommended Land Fattern (FC) | 0.90mm to 1.20mm(Reflow Soldering) |

| Electrical Characteristics   |           |  |
|------------------------------|-----------|--|
| Capacitance                  | 47nF ±10% |  |
| Rated Voltage                | 100VDC    |  |
| Temperature Characteristic   | X7R(±15%) |  |
| Dissipation Factor (Max.)    | 3%        |  |
| Insulation Resistance (Min.) | 10000ΜΩ   |  |

| Other                 |                                       |  |  |
|-----------------------|---------------------------------------|--|--|
| Operating Temp. Range | -55 to 125°C                          |  |  |
| Coldonian Mathead     | Wave (Flow)                           |  |  |
| Soldering Method      | Reflow                                |  |  |
| AEC-Q200              | NO                                    |  |  |
| Packing               | Embossed (Plastic)Taping [180mm Reel] |  |  |
| Package Quantity      | 2000pcs                               |  |  |

<sup>!</sup> Images are for reference only and show exemplary products.

<sup>!</sup> This PDF document was created based on the data listed on the TDK Corporation website. ! All specifications are subject to change without notice.



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FIT (Failure In Time)



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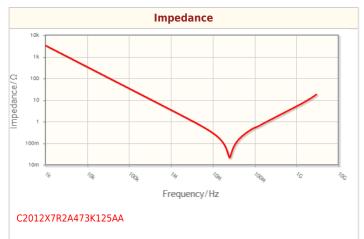
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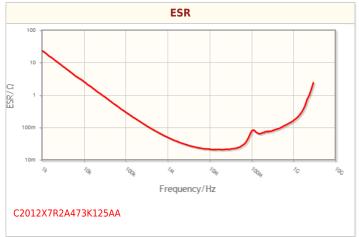


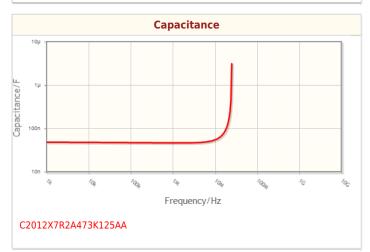
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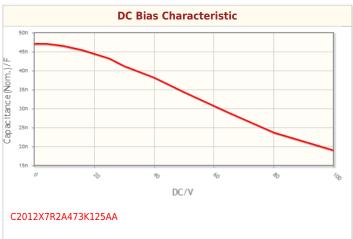
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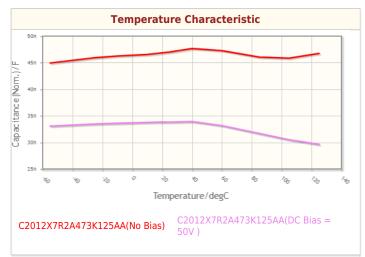
# Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

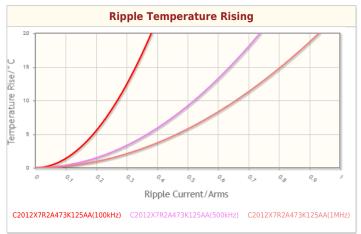












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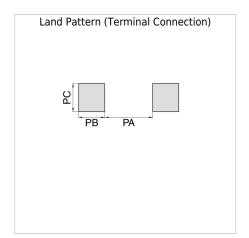
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# **Associated Images**



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